

ABSTRACT OF THE DISCLOSURE

The spaces in chuck grooves 3a and 3b are evacuated to
chuck the entire surface of a wafer 1 to the chuck surface
5 of a wafer support table 3 and curve the wafer 1. A wafer
2 is horizontally opposed to the wafer 1, and the center of
the wafer 2 is pressed by a press pin 6a. The centers of the
two wafers 1 and 2 are contacted, and the contact portion
gradually spreads to the vicinity of the periphery of a
10 central portion 3c and takes a substantially circular shape.
After that, the chuck by the chuck grooves 3a is stopped.
Consequently, the wafer 1 flattens, and the entire surfaces
of the wafers 1 and 2 are contacted.

This Sheet Has Been Replaced

